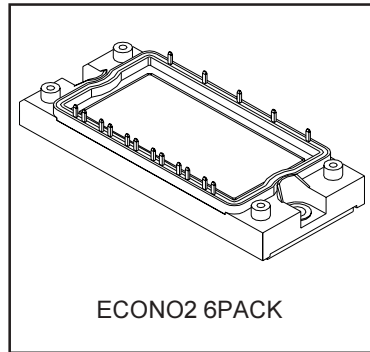


IGBT SIXPACK MODULE

Features

- Low $V_{CE(on)}$ Non Punch Through IGBT Technology
- Low Diode V_F
- 10 μ s Short Circuit Capability
- Square RBSOA
- HEXFRED Antiparallel Diode with Ultrasoft Reverse Recovery Characteristics
- Positive $V_{CE(on)}$ Temperature Coefficient
- Ceramic DBC Substrate
- Low Stray Inductance Design




$V_{CES} = 1200V$

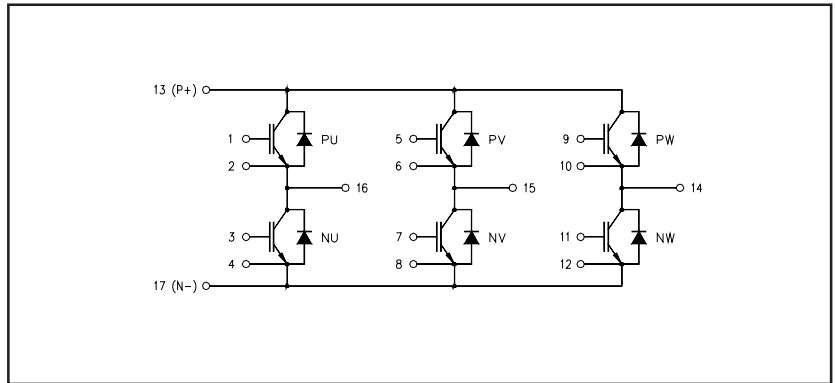
$I_C = 13A @ T_C = 80^\circ C$

$t_{sc} > 10\mu s @ T_J = 150^\circ C$

$V_{CE(on)}$ typ. = 2.64V

Benefits

- Benchmark Efficiency for Motor Control
- Rugged Transient Performance
- Low EMI, Requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Low Junction to Case Thermal Resistance
- UL Approved E78996 



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	20	A
$I_C @ T_C = 80^\circ C$	Continuous Collector Current	13	
I_{CM}	Pulsed Collector Current (Ref. Fig. C.T.5)	40	
I_{LM}	Clamped Inductive Load Current	40	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	20	
$I_F @ T_C = 80^\circ C$	Diode Continuous Forward Current	12	
I_{FM}	Diode Maximum Forward Current	40	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation (IGBT and Diode)	151	W
$P_D @ T_C = 80^\circ C$	Maximum Power Dissipation (IGBT and Diode)	85	
T_J	Maximum Operating Junction Temperature	150	$^\circ C$
T_{STG}	Storage Temperature Range	-40 to +125	
V_{ISOL}	Isolation Voltage	AC 2500 (MIN)	V

Thermal and Mechanical Characteristics

	Parameter	Min	Typical	Maximum	Units
$R_{\theta JC}$ (IGBT)	Junction-to-Case IGBT	-	-	1.42	$^\circ C/W$
$R_{\theta JC}$ (Diode)	Junction-to-Case Diode	-	-	1.97	
$R_{\theta CS}$ (Module)	Case-to-Sink, flat, greased surface	-	0.05	-	
	Mounting Torque (M5)	2.7	-	3.3	N*m
	Weight	-	170	-	g

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV _(CES)	Collector-to-Emitter Breakdown Voltage	1200	-	-	V	V _{GE} = 0 I _C = 500μA
ΔV _{(BR)CES/ΔT_J}	Temp. Coefficient of Breakdown Voltage	-	0.87	-	V/°C	V _{GE} = 0 I _C = 1mA (25°C - 125°C)
V _{CE(ON)}	Collector-to-Emitter Voltage	-	2.64	2.85	V	I _C = 10A V _{GE} = 15V
		-	3.59	3.94		I _C = 20A V _{GE} = 15V
		-	3.17	3.46		I _C = 10A V _{GE} = 15V T _J = 125°C
		-	4.48	4.97		I _C = 20A V _{GE} = 15V T _J = 125°C
V _{GE(th)}	Gate Threshold Voltage	4	-	6		V _{CE} = V _{GE} I _C = 250μA
ΔV _{GE(th)/ΔT_J}	Threshold Voltage temp. coefficient	-	-10.4	-	mV/°C	V _{CE} = V _{GE} I _C = 1mA (25°C-125°C)
I _{CES}	Zero Gate Voltage Collector Current	-	-	100	μA	V _{GE} = 0 V _{CE} = 1200V
		-	750	-		V _{GE} = 0 V _{CE} = 1200V T _J = 125°C
V _{FM}	Diode Forward Voltage Drop	-	2.00	2.28	V	I _F = 10A
		-	2.48	2.90		I _F = 20A
		-	2.16	2.51		I _F = 10A T _J = 125°C
		-	2.87	3.42		I _F = 20A T _J = 125°C
I _{GES}	Gate-to-Emitter Leakage Current	-	-	±200	nA	V _{GE} = ±20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q _G	Total Gate Charge (turn-on)	-	48	75	nC	I _C = 10A
Q _{GE}	Gate-to-Emitter Charge (turn-on)	-	8	15		V _{CC} = 600V
Q _{GC}	Gate-to-Collector Charge (turn-on)	-	22	33		V _{GE} = 15V
E _{ON}	Turn-On Switching Loss	-	0.84	1.26	mJ	I _C = 10A V _{CC} = 600V
E _{OFF}	Turn-Off Switching Loss	-	0.36	0.54		V _{GE} = 15V R _G = 22Ω L = 1mH
E _{TOT}	Total Switching Loss	-	1.20	1.81		T _J = 25°C ①
E _{ON}	Turn-On Switching Loss	-	1.14	1.71	mJ	I _C = 10A V _{CC} = 600V
E _{OFF}	Turn-Off Switching Loss	-	0.64	0.96		V _{GE} = 15V R _G = 22Ω L = 1mH
E _{TOT}	Total Switching Loss	-	1.78	2.67		T _J = 125°C ①
t _{d(on)}	Turn-On delay time	-	83	124	ns	I _C = 10A V _{CC} = 600V
t _r	Rise time	-	21	32		V _{GE} = 15V R _G = 22Ω L = 1mH
t _{d(off)}	Turn-Off delay time	-	115	172		T _J = 125°C
t _f	Fall time	-	279	420		
C _{ies}	Input Capacitance	-	750	1150	pF	V _{GE} = 0
C _{oes}	Output Capacitance	-	190	290		V _{CC} = 30V
C _{res}	Reverse Transfer Capacitance	-	20	35		f = 1Mhz
RBSOA	Reverse Bias Safe Operating Area	FULLSQUARE				T _J = 150°C I _C = 40A R _G = 22Ω V _{GE} = 15V to 0
SCSOA	Short Circuit Safe Operating Area	10	-	-	μs	T _J = 150°C V _{CC} = 960V V _P = 1200V R _G = 22Ω V _{GE} = 15V to 0
I _{rr}	Diode Peak Rev. Recovery Current	-	22	-	A	T _J = 125°C V _{CC} = 600V I _F = 10A L = 1mH V _{GE} = 15V R _G = 22Ω

① Energy losses include "tail" and diode reverse recovery.

Inverter

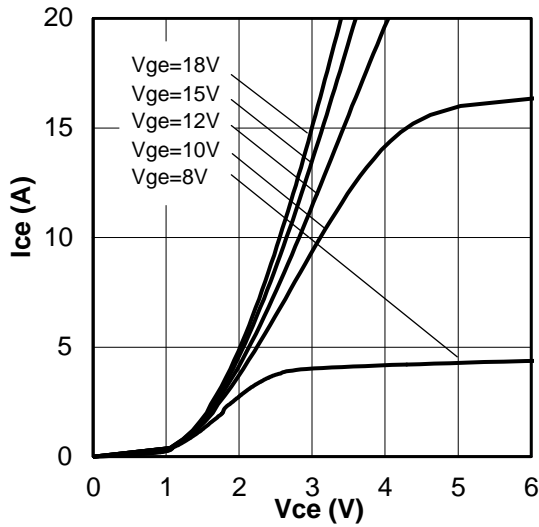


Fig. 1 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}; t_p = 80\mu\text{s}$

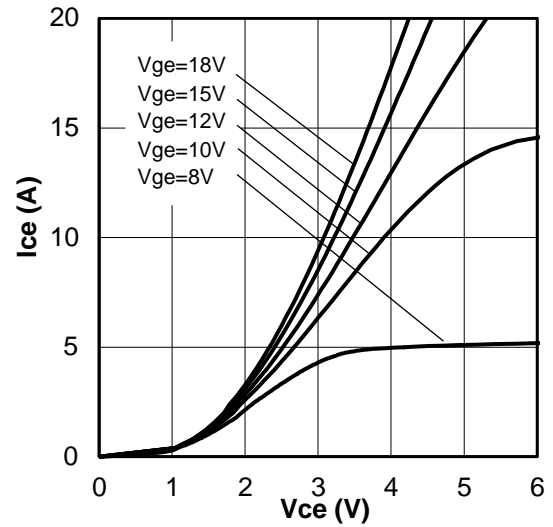


Fig. 2 - Typ. IGBT Output Characteristics
 $T_J = 125^\circ\text{C}; t_p = 80\mu\text{s}$

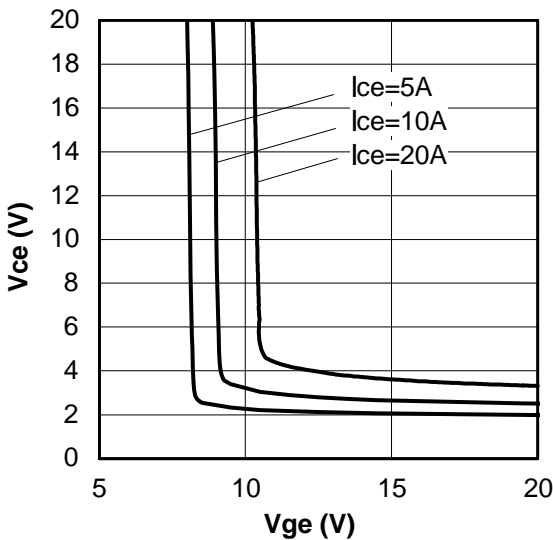


Fig. 3 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

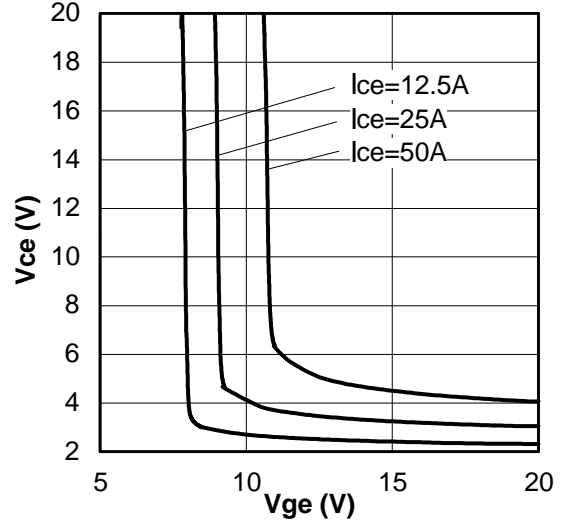


Fig. 4 - Typical V_{CE} vs. V_{GE}
 $T_J = 125^\circ\text{C}$

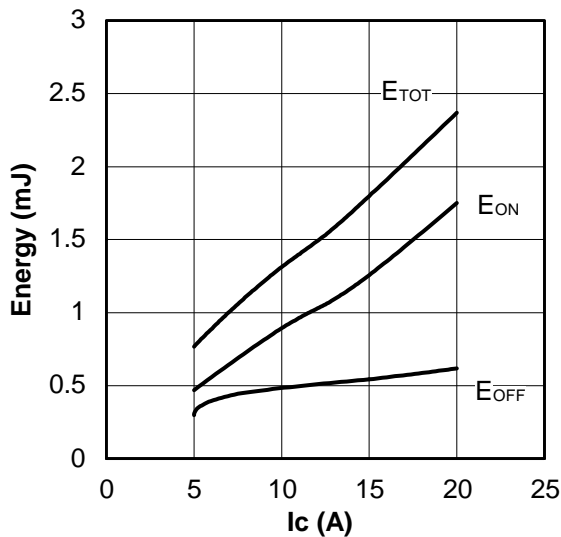


Fig. 5 - Typ. Energy Loss vs. I_C
 $T_J = 125^\circ\text{C}; L = 1\text{mH}; V_{CE} = 600\text{V}$
 $R_G = 22\Omega; V_{GE} = 15\text{V}$

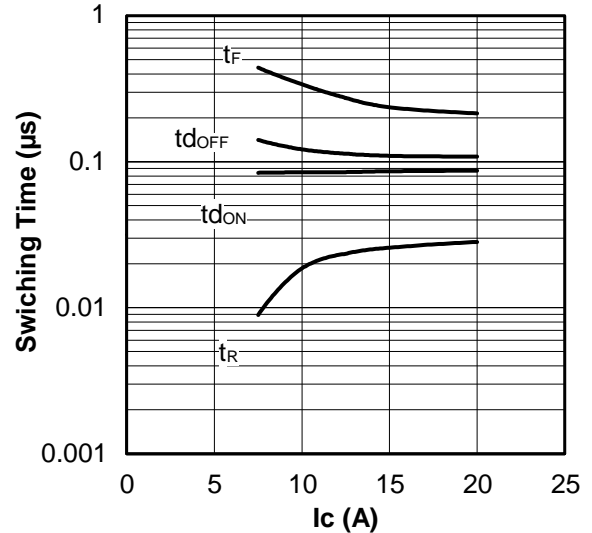


Fig. 6 - Typ. Switching Time vs. I_C
 $T_J = 125^\circ\text{C}; L = 1\text{mH}; V_{CE} = 600\text{V}$
 $R_G = 22\Omega; V_{GE} = 15\text{V}$

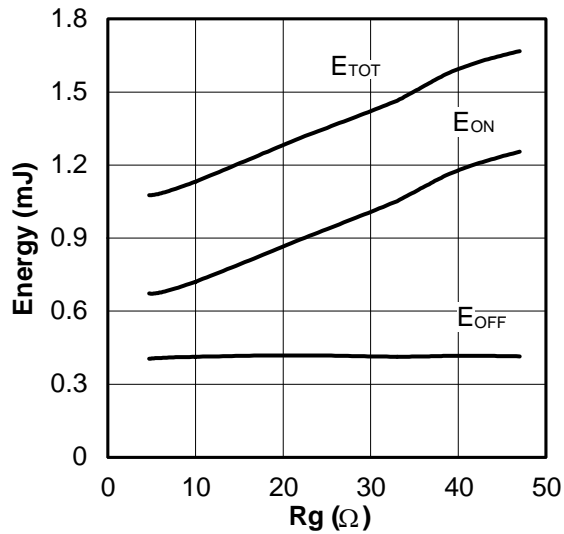


Fig. 7 - Typ. Energy Loss vs. R_G
 $T_J = 125^\circ\text{C}$; $L = 1\text{mH}$; $V_{CE} = 600\text{V}$
 $I_{CE} = 10\text{A}$; $V_{GE} = 15\text{V}$

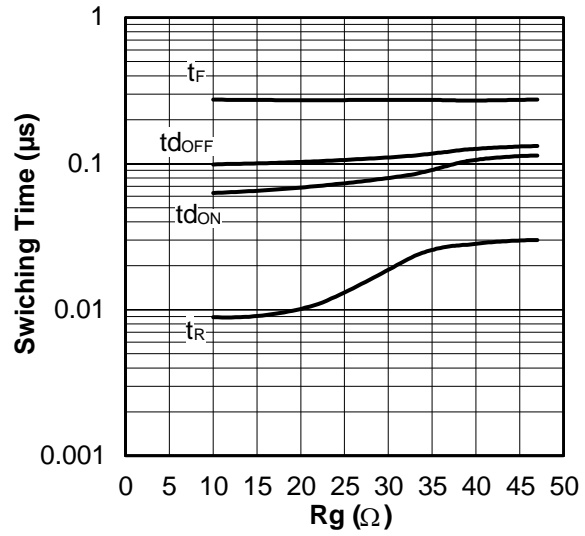


Fig. 8 - Typ. Switching Time vs. R_G
 $T_J = 125^\circ\text{C}$; $L = 1\text{mH}$; $V_{CE} = 600\text{V}$;
 $I_{CE} = 10\text{A}$; $V_{GE} = 15\text{V}$

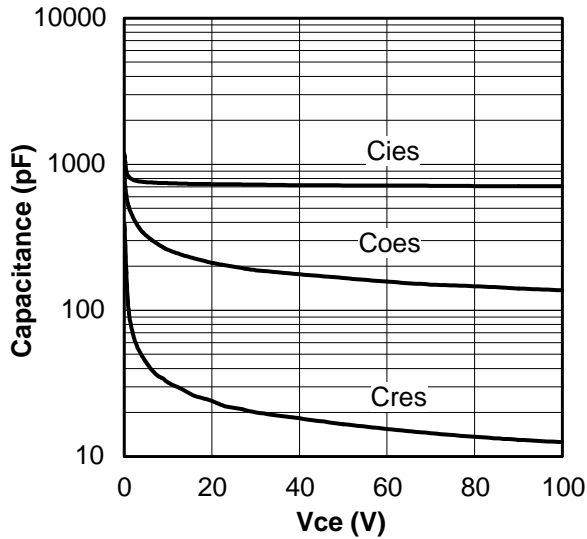


Fig. 9 - Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0$; $f = 1\text{MHz}$

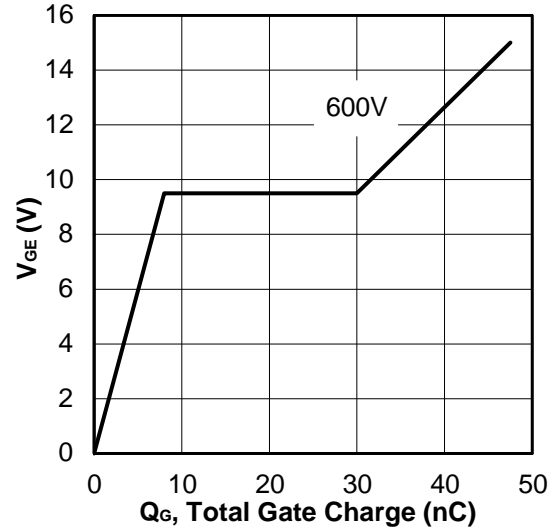


Fig. 10 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 10\text{A}$

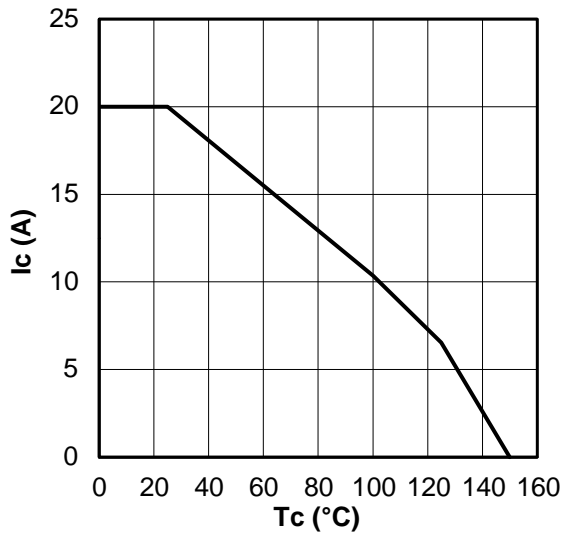


Fig. 11 - Maximum DC Collector Current vs. Case Temperature

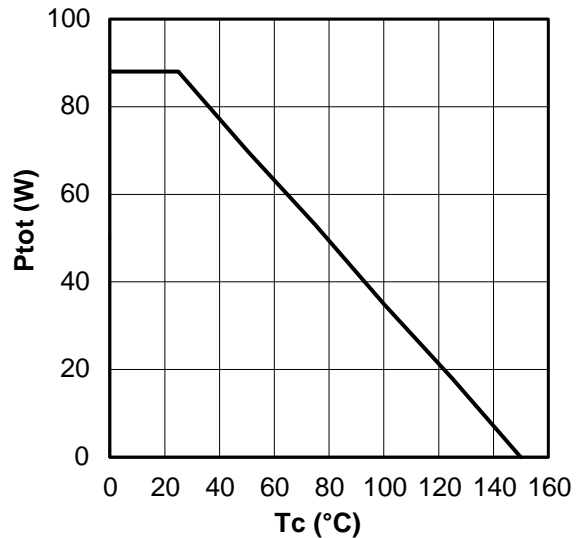


Fig. 12 - Power Dissipation vs. Case Temperature

Inverter

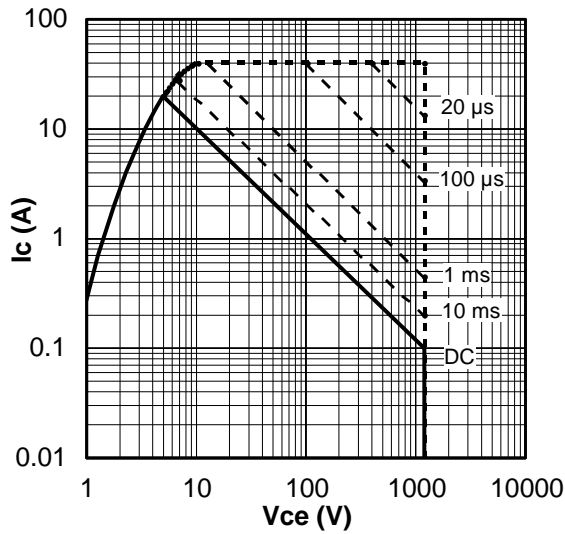


Fig. 13 - Forward SOA
 $T_C = 25^\circ\text{C}; T_J \leq 150^\circ\text{C}$

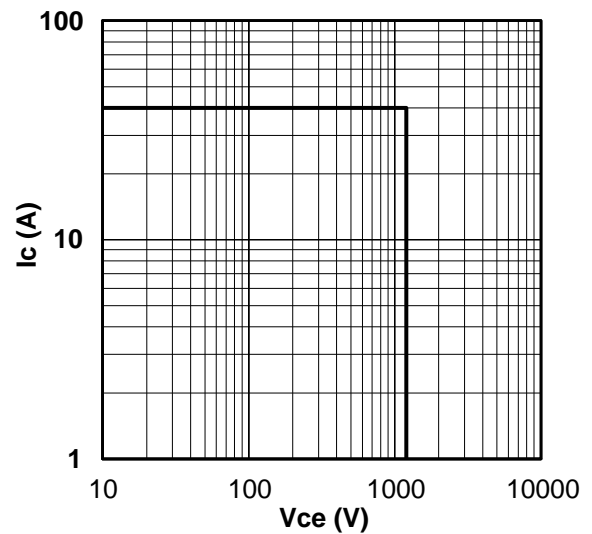


Fig. 14 - Reverse Bias SOA
 $T_J = 150^\circ\text{C}; V_{GE} = 15\text{V}$

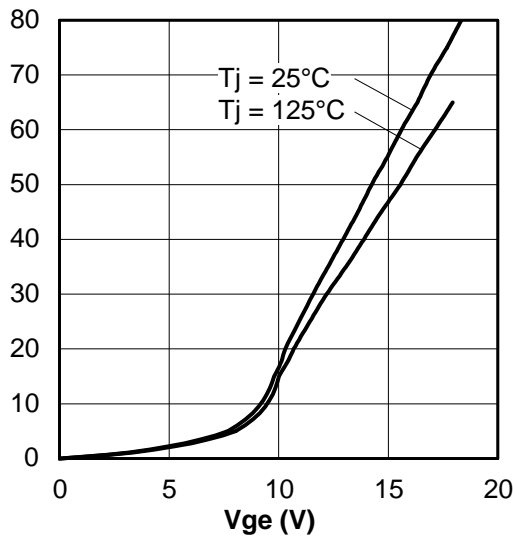


Fig. 15 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}; t_p = 10\mu\text{s}$

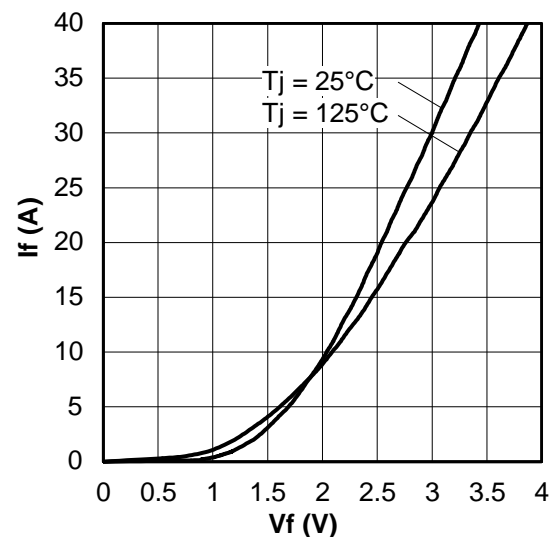


Fig. 16 - Typ. Diode Forward Characteristics
 $t_p = 80\mu\text{s}$

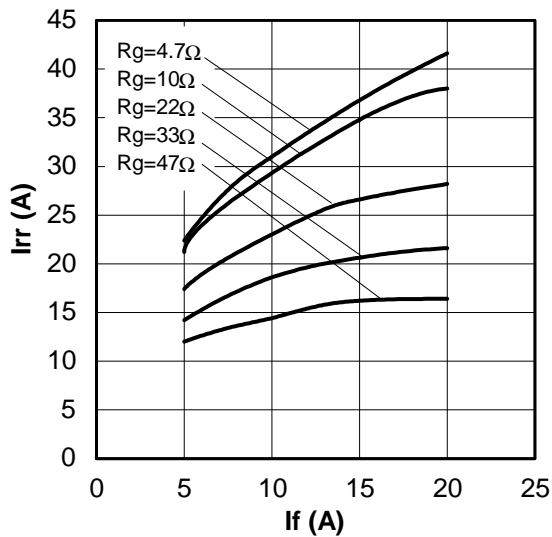


Fig. 17 - Typical Diode I_{RR} vs. I_F
 $T_J = 125^\circ\text{C}$

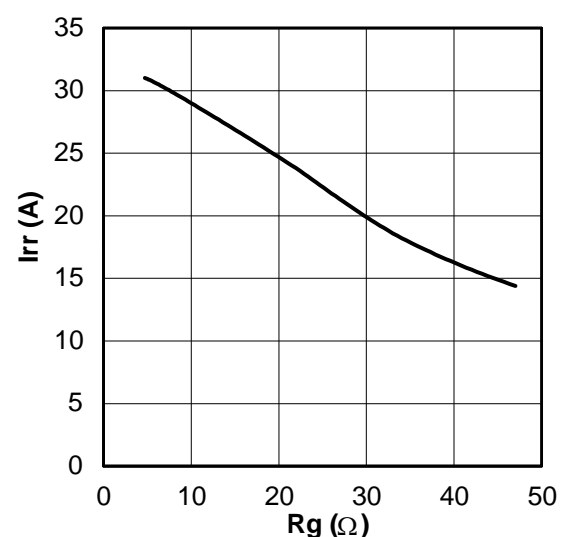


Fig. 18 - Typical Diode I_{RR} vs. R_G
 $T_J = 125^\circ\text{C}; I_F = 10\text{A}$

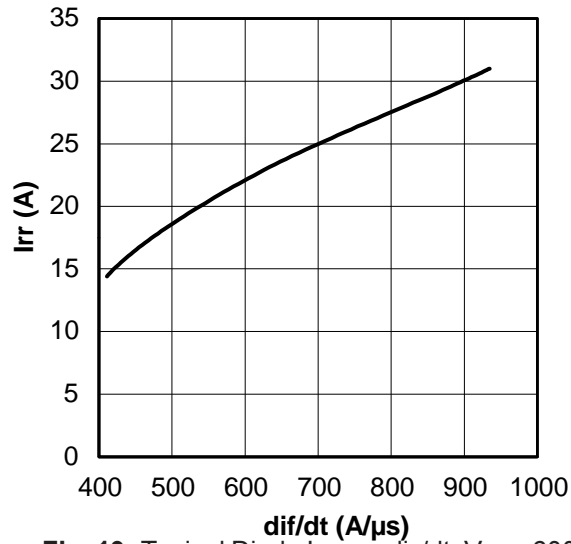


Fig. 19- Typical Diode I_{RR} vs. di_F/dt ; $V_{CC}=600V$;
 $V_{GE}=15V$; $I_{CE}=10A$; $T_J=125^{\circ}C$

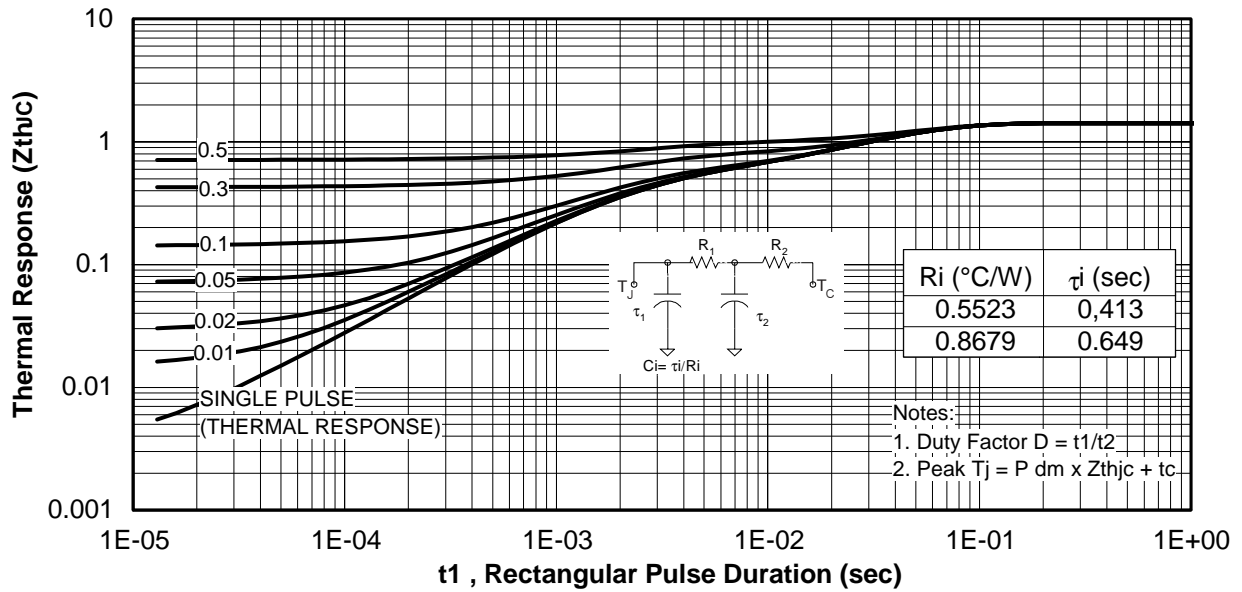


Fig 20. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

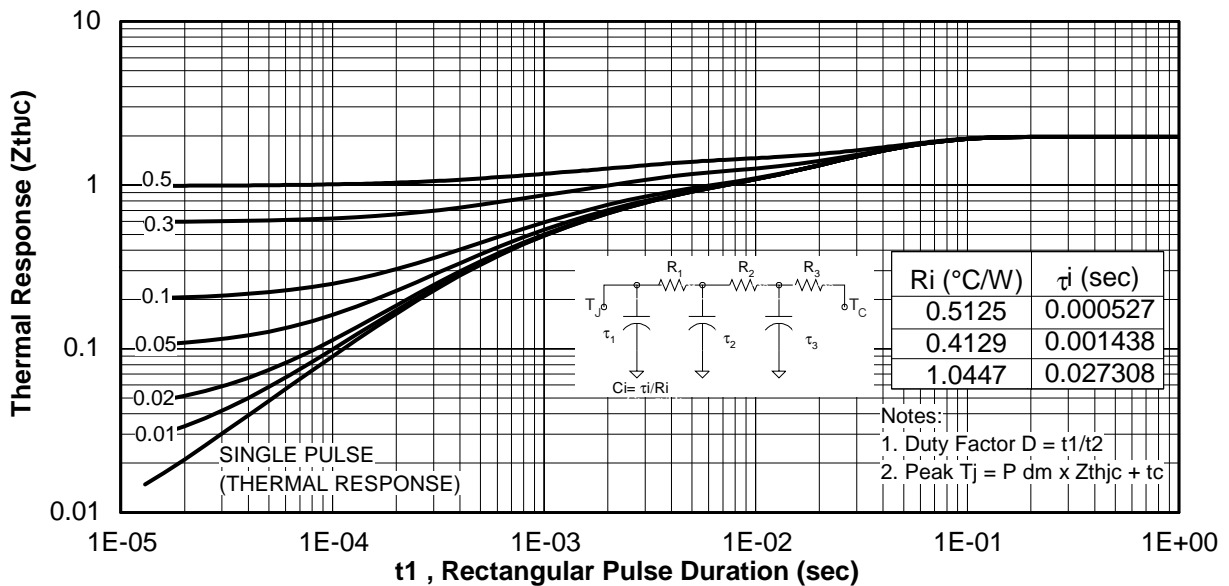


Fig 21. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

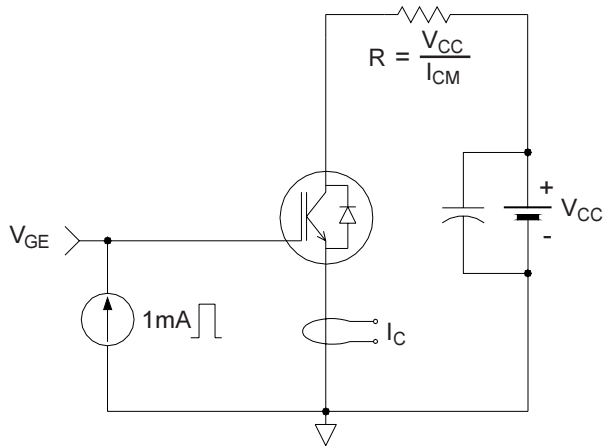


Fig.C.T.1 - Gate Charge Circuit (turn-off)

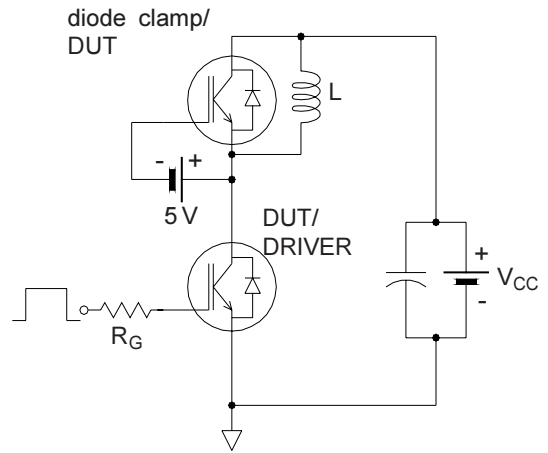


Fig.C.T.2 - RBSOA Circuit

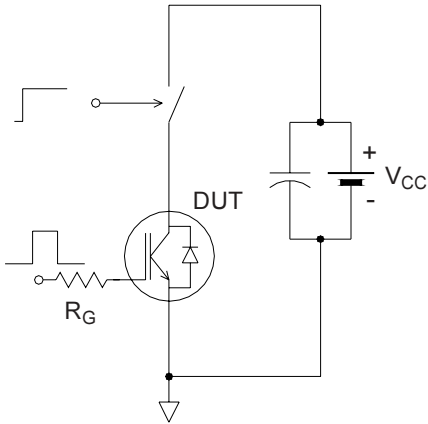


Fig.C.T.3 - S.C. SOA Circuit

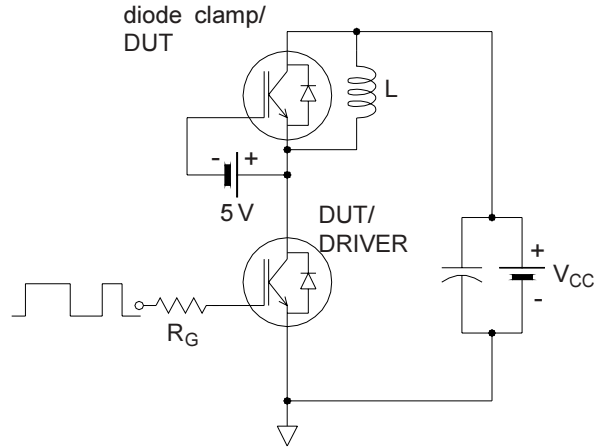


Fig.C.T.4 - Switching Loss Circuit

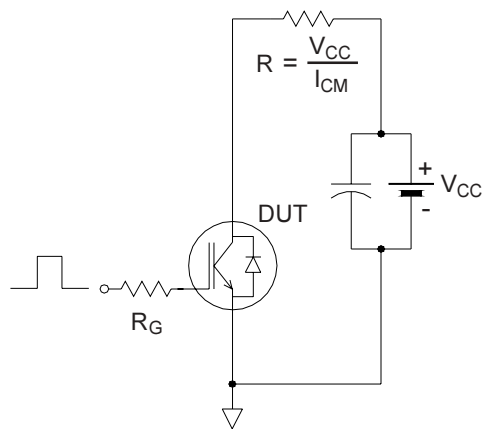


Fig.C.T.5 - Resistive Load Circuit

